

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination WADA ET AL.	
		Examiner Paul D. Kim	Art Unit 3729	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,759,258	07-2004	Kasukabe et al.	438/17
*	B	US-6,696,849	02-2004	Ban et al.	324/760
*	C	US-3,605,230	09-1971	_____	492/53
*	D	US-6,147,505	11-2000	Ott et al.	324/754
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	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.